

Declaration of Conformity to EU RoHS Directive(EU) 2015/863

Pulse Electronics 15255 Innovation Drive #100 San Diego, CA 92128 Tel: 858-674-8100

Part number:

PE-67540NL

This is to certify that the parts/products listed above meet the requirements of the **RoHS Directive** 2015/863. The following table lists the restricted materials and their respective allowable limits:

RoHS Restricted Substance	Allowable Limit
Cadmium and its compounds*	100 ppm (0.01 weight %)
Mercury and its compounds	1000 ppm (0.1 weight %)
Hexavalent chromium and its	1000 ppm (0.1 weight %)
compounds	
Lead and its compounds **	1000 ppm (0.1 weight %)
Polybrominated biphenyls (PBB)	1000 ppm (0.1 weight %)
Polybrominated diphenyl ethers	1000 ppm (0.1 weight %)
(PBDE)	
Phthalate (2 - ethyl hexyl ester (DEHP)	1000 ppm (0.1 weight %)
Butyl Benzyl Phthalate (BBP)	1000 ppm (0.1 weight %)
dibutyl phthalate (DBP)	1000 ppm (0.1 weight %)
Di Iso Butyl Ortho Phthalate (DIBP)	1000 ppm (0.1 weight %)

If parts/products take advantage of any exceptions, please check which exemption(s):
1. Mercury in single capped (compact) fluorescent lamps not exceeding (per burner):
(a) For general lighting purposes < 30 Watts
\square (b) For general lighting purposes \geq 30 Watts and $<$ 50 Watts
\Box (c) For general lighting purposes \geq 50 Watts and $<$ 150 Watts
(d) For general lighting purposes ≥150 Watts: 15 mg
(e) For general lighting purposes with circular or square structural shape and tube diameter ≤17
mm
(f) For special purposes: 5 mg
2a. Mercury in double-capped linear fluorescent lamps for general lighting purposes not exceeding
(per lamp):
(1) Tri-band phosphor with normal lifetime and a tube diameter < 9 mm (e.g. T2)
\square (2) Tri-band phosphor with normal lifetime and a tube diameter ≥ 9 mm and ≤ 17 mm
(e.g. T5)
\square (3) Tri-band phosphor with normal lifetime and a tube diameter > 17 mm and \leq 28 mm
(e.g. T8)
(4) Tri-band phosphor with normal lifetime and a tube diameter > 28 mm (e.g. T12)

\square (5) Tri-band phosphor with long lifetime ($\ge 25,000h$)
2b. Mercury in other fluorescent lamps not exceeding (per lamp): ☐ (1) Linear halophosphate lamps with tube diameter > 28mm (e.g. T10 and T12): 10 mg ☐ (2) Non-linear halophoshate lamps (all diameters): 15mg ☐ (3) Non-linear tri-band phosphor lamps with tube diameter > 17 mm (e.g. T9) ☐ (4) Lamps for other general lighting and special purposes (e.g. induction lamps)
3. Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes not exceeding (per lamp): ☐ (a) Short length (≤500 mm) ☐ (b) Medium length (> 500 mm and ≤1500 mm) ☐ (c) Long length (> 1500 mm)
4a. Mercury in other low pressure discharge lamps (per lamp)
4b. Mercury in High Pressure Sodium (vapor) lamps for general lighting purposes not exceeding (per burner) in lamps with improved color rendering index Ra > 60: \square (I) $P \le 155$ W \square (II) $155 < P \le 405$ W \square (III) $P > 405$ W
4c. Mercury in other High Pressure Sodium (vapor) lamps for general lighting purposes not exceeding (per burner):
☐ 4d. Mercury in High Pressure Mercury (vapor) lamps (HMPV) ☐ 4e. Mercury in metal halide lamps (MH) ☐ 4f. Mercury in other discharge lamps for special purposes not specifically mentioned in Annex
 5a. Lead in glass of cathode ray tubes 5b. Lead in glass of fluorescent tubes not exceeding 0.2% by weight
☐ 6a. Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight ☐ 6b. Lead as an alloying element in aluminium containing up to 0.4% lead by weight ☐ 6c. Copper alloy containing up to 4% lead by weight
\square 7a. Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
☐ 7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications
☐ 7c-I. Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound ☐ 7c-II. Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher

250 V DC
 8a. Cadmium and its compounds in one shot pellet type thermal cut-offs 8b. Cadmium and its compounds in electrical contacts
\square 9. Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0.75% by weight in the cooling solution
9b. Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and refrigeration (HVACR) applications
11a. Lead used in C-press compliant pin connector systems
11b. Lead used in other than C-press compliant pin connector systems
12. Lead as a coating material for the thermal conduction module C-ring
 13a. Lead in white glasses used for optical applications 13b. Cadmium and lead in filter glasses and glasses used for reflectance standards
14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight
☐ 15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages
☐ 16. Lead in linear incandescent lamps with silicate coated tubes
17. Lead halide as radiant agent in High Intensity Discharge (HID) lamps used for professional reprography applications
18a. Lead as activator in the fluorescent powder (1% lead by weight or less) of discharge lamps when used as specialty lamps for diazoprinting reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr,Ba) 2MgSi2O7:Pb)
☐ 18b. Lead as activator in the fluorescent powder (1% lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi2O5:Pb)
☐ 19. Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact Energy Saving Lamps (ESL)
20. Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCDs)
21. Lead and cadmium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses

23. Lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm and less

7c-III. Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 VAC or

24. Lead in solders for the sceramic multilayer capacitors	soldering to machined through hole discoidal and planar array
25. Lead oxide in surface conotably in the seal frit and frit	onduction electron emitter displays (SED) used in structural elements, ring
☐ 26. Lead oxide in the glass	envelope of Black Light Blue lamps
· ·	ansducers used in high-powered (designated to operate for several of 125dB SPL and above) loudspeakers
29. Lead bound in crystal g Directive 69/493/EEC	lass as defined in Annex I (Categories 1, 2, 3 and 4) of Council
	trical/mechanical solder joints to electrical conductors located nsducers used in high-powered loudspeakers with sound pressure
31. Lead in soldering mater liquid crystal displays, design of	rials in mercury free flat fluorescent lamps (which e.g. are used for or industrial lighting)
32. Lead oxide in seal frit u tubes	sed for making window assemblies for Argon and Krypton laser
33. Lead in solders for the stransformers	soldering of thin copper wires of 100 µm diameters and less in power
34. Lead in cermet-based tr	immer potentiometer elements
36. Mercury used as a cathode to 30 mg per display until 1 Ju	sputtering inhibitor in DC plasma displays with a content up ly 2010
☐ 37. Lead in the plating laye	r of high voltage diodes on the basis of a zinc borate glass body
38. Cadmium and cadmium oxide	oxide in thick film pastes used on aluminium bonded beryllium
	erting II-VI LEDs (< 10 μg Cd per mm ² of light-emitting area) for or display systems until 1 July 2014
Signature: Fewin	Date: 2/6/2018
Name: Kevin Zhou	Phone: 86-769-85538871
Title: Manager	Email: kevinzhou@pulseelectronic.com

ПОСТАВКА ЭЛЕКТРОННЫХ КОМПОНЕНТОВ

многоканальный

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001 Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

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Офис по работе с юридическими лицами:

105318, г. Москва, ул. Щербаковская д. 3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru moschip.ru_6 moschip.ru 4 moschip.ru 9